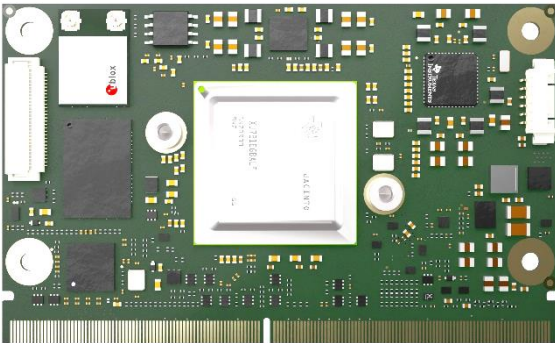


# TI TDA4VM SMARC – Accelerated Computing

## conga-STDA4

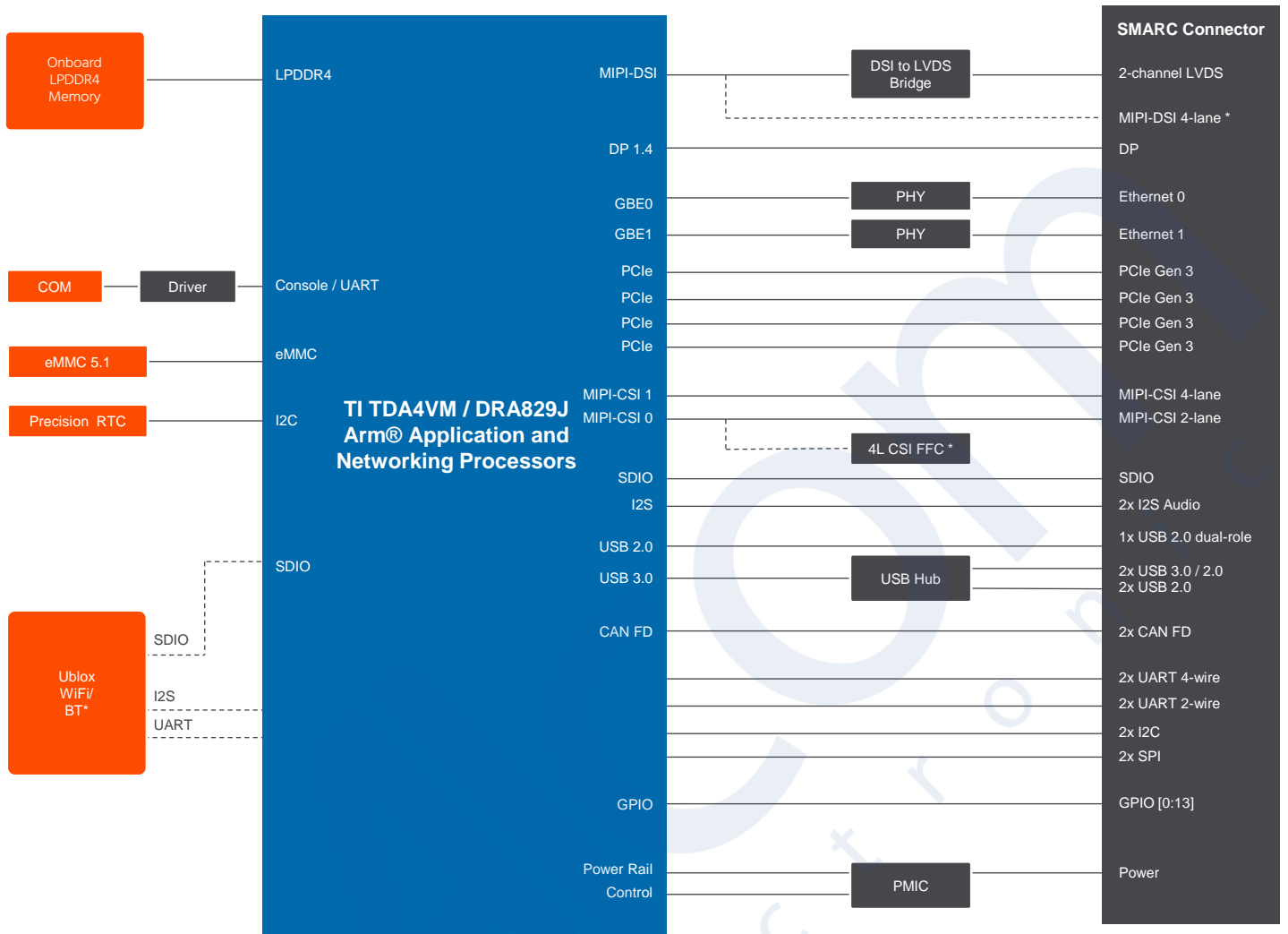


- SMARC Module based on TI TDA4VM application processor and DRA829J Arm® networking processor
- Heterogenous architecture with dual Arm® Cortex®-A72, DSP and accelerators for deep learning and multimedia
- Arm® Cortex®-R5F MCUs to offload real-time communication
- Highest reliability for harsh environment applications
- Industrial temperature range -40°C .. +85°C



<b>Form factor</b>	SMARC Module Specification 2.1																		
<b>CPU SoC</b>	<b>TI TDA4VM and DRA829J Arm® Application and Networking Processors</b>																		
	<table border="1"> <thead> <tr> <th></th> <th>Arm Cortex-A72</th> <th>ARM Cortex-R5F</th> <th>DSP Cores</th> <th>MMA</th> <th>GPU</th> </tr> </thead> <tbody> <tr> <td><b>TDA4VM</b></td> <td>2x @ 2.0 GHz</td> <td>6x @ 1.0 GHz</td> <td>1x C7x up to 80 GFLOPs</td> <td>Deep Learning</td> <td>3D PowerVR</td> </tr> <tr> <td><b>DRA829J</b></td> <td>2x @ 2.0 GHz</td> <td>6x @ 1.0 GHz</td> <td>2x C66 up to 40 GFLOPs</td> <td>Up to 8 TOPS</td> <td>Rogue 8XE GE8430</td> </tr> </tbody> </table>		Arm Cortex-A72	ARM Cortex-R5F	DSP Cores	MMA	GPU	<b>TDA4VM</b>	2x @ 2.0 GHz	6x @ 1.0 GHz	1x C7x up to 80 GFLOPs	Deep Learning	3D PowerVR	<b>DRA829J</b>	2x @ 2.0 GHz	6x @ 1.0 GHz	2x C66 up to 40 GFLOPs	Up to 8 TOPS	Rogue 8XE GE8430
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<b>DRAM</b>	Up to 8 GB onboard LPDDR4x memory   3733 MT/s   inline ECC Up to 8 MB of on-chip L3 RAM with ECC and coherency   512KB on-chip SRAM in MAIN domain, protected by ECC																		
<b>Ethernet</b>	2x Gbit Ethernet with IEEE 1588 support																		
<b>I/O Interfaces</b>	1x dual-role USB 2.0   2x USB 2.0   2x USB 3.0   1x SDIO 3.0   2x PCIe 3.0 x1 + 1x PCIe 3.0 x2 or up to 4x PCIe 3.0 x1   2x GP I <sup>2</sup> C   2x SPI   4x UART (2x with Handshake)   2x CAN FD   14x GPIO   optional full industrial onboard Ublox WiFi/BT module																		
<b>Mass Storage</b>	eMMC 5.1 up to 128 GB configurable as pseudo-SLC																		
<b>Sound</b>	2x I <sup>2</sup> S																		
<b>Graphics</b>	Integrated in SoC   Graphics Accelerator 3D GPU PowerVR Rogue 8XE GE8430   up to 1x Ultra-HD or 4x Full-HD 60fps display resolution   Up to 2 independent display outputs   VPU up to 4k60p H.264 encode / Full-HD H.265 decode   OpenGL ES 3.1   Open VX   OpenCL																		
<b>Video Interfaces</b>	1x dual channel 24-bit LVDS   1x Display Port 1.4 supports up to 3 Full HD 1080p displays via MST   optional 1x MIPI-DSI 4-lane shared with LVDS   2x MIPI-CSI 4-lanes   2x integrated Image Signal Processor (ISP) for MIPI-CSI camera																		
<b>Features</b>	Watchdog Timer   Console Port   High Precision Real Time Clock																		
<b>AI &amp; Deep Learning</b>	Deep-learning Matrix Multiply Accelerator Accelerators (MMA) with up to 8 TOPS   C7x floating point, vector DSP with up to 80GFLOPs   Vision Processing Accelerators (VPAC) with Image Signal Processor (ISP) and multiple vision assist accelerators   Depth and Motion Processing Accelerators (DMPAC)																		
<b>Security</b>	Customer programmable root key, up to RSA-4K or ECC-512   Crypto hardware accelerators, PKA with ECC, AES, SHA, RNG, DES and 3DES   High Assurance Boot support (optional)   SHE, Encryption Engine AES-128, AES-256, TRNG, SHA-1, SHA-2, SHA-256, MD-5   RSA-1024, 2048, 3072, 4096 and secure key storage																		
<b>Boot Loader</b>	U-Boot boot loader																		
<b>Operating Systems</b>	Linux   QNX   RTOS   VxWorks																		
<b>Power Consumption</b>	Typ. application 5-10W @ 5V																		
<b>Temperature Range</b>	Operating Temperature Range: -40 to +85°C industrial grade Storage Temperature Range: -40 to +85°C																		
<b>Humidity</b>	Operating: 10 - 90% r. H. non cond.      Storage: 5 - 95% r. H. non cond.																		
<b>Size</b>	82 x 50 mm (3,23" x 1,97")																		

# conga-STDA4 | Block Diagram



\* Assembly Option

# conga-STDA4 | Order Information

Article	PN	Description
conga-STDA4/i-TDA4VM-4G eMMC32	051510	SMARC Module based on high-performance industrial TI TDA4VM Arm® Application processor. Features 2x ARM Cortex-A72 @ 2.0GHz + 6x ARM Cortex-R5F + 8 TOPS MMA (deep-learning matrix multiply accelerator), 4GB onboard LPDDR4x memory and 32GB onboard eMMC. Industrial grade temperature range from -40°C to 85°C.
conga-STDA4/i-TDA4VM-2G eMMC32	051511	SMARC Module based on high-performance industrial TI TDA4VM Arm® Application processor. Features 2x ARM Cortex-A72 @ 2.0GHz + 6x ARM Cortex-R5F + 8 TOPS MMA (deep-learning matrix multiply accelerator), 2GB onboard LPDDR4x memory and 32GB onboard eMMC. Industrial grade temperature range from -40°C to 85°C.
conga-STDA4/i-DRA829J-4G eMMC32	051512	SMARC Module based on high-performance industrial TI DRA829J Arm® Networking processor. Features 2x ARM Cortex-A72 @ 2.0GHz + 6x ARM Cortex-R5F, 4GB onboard LPDDR4x memory and 32GB onboard eMMC. Industrial grade temperature range from -40°C to 85°C.
conga-STDA4/i-DRA829J-2G eMMC32	051513	SMARC Module based on high-performance industrial TI DRA829J Arm® Networking processor. Features 2x ARM Cortex-A72 @ 2.0GHz + 6x ARM Cortex-R5F, 2GB onboard LPDDR4x memory and 32GB onboard eMMC. Industrial grade temperature range from -40°C to 85°C.
conga-STDA4/CSP-B	051550	Passive cooling solution for SMARC Module conga-STDA4 based on TI TDA4VM and DRA829J Arm® processors. All standoffs are with 2.7 mm bore hole.
conga-STDA4/HSP-B	051551	Standard heatspreader for SMARC Module conga-STDA4 based on TI TDA4VM and DRA829J Arm® processors. All standoffs are with 2.7 mm bore hole.
SMARC/CSA Adapter	050060	Active cooling solution adapter for SMARC modules used in combination with module heat spreader.
conga-SEVAL	007010	Evaluation carrier board for SMARC modules.
conga-SMC1/SMARC-ARM	020750	3.5" carrier board for congatec SMARC modules based on ARM architecture.

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